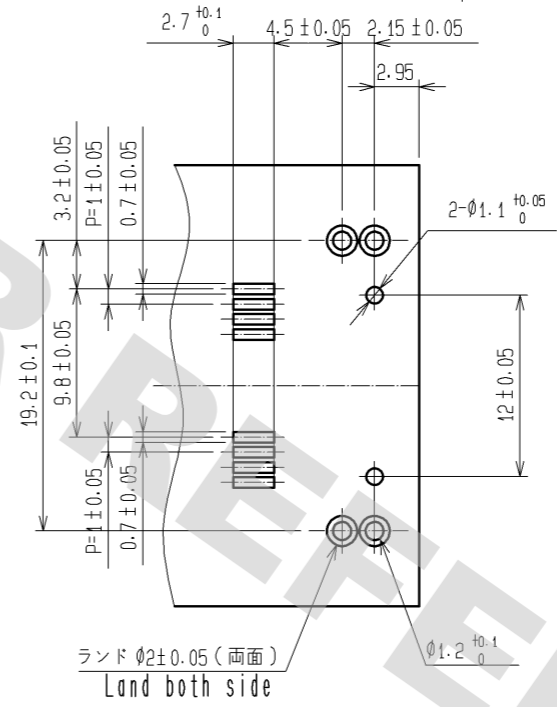
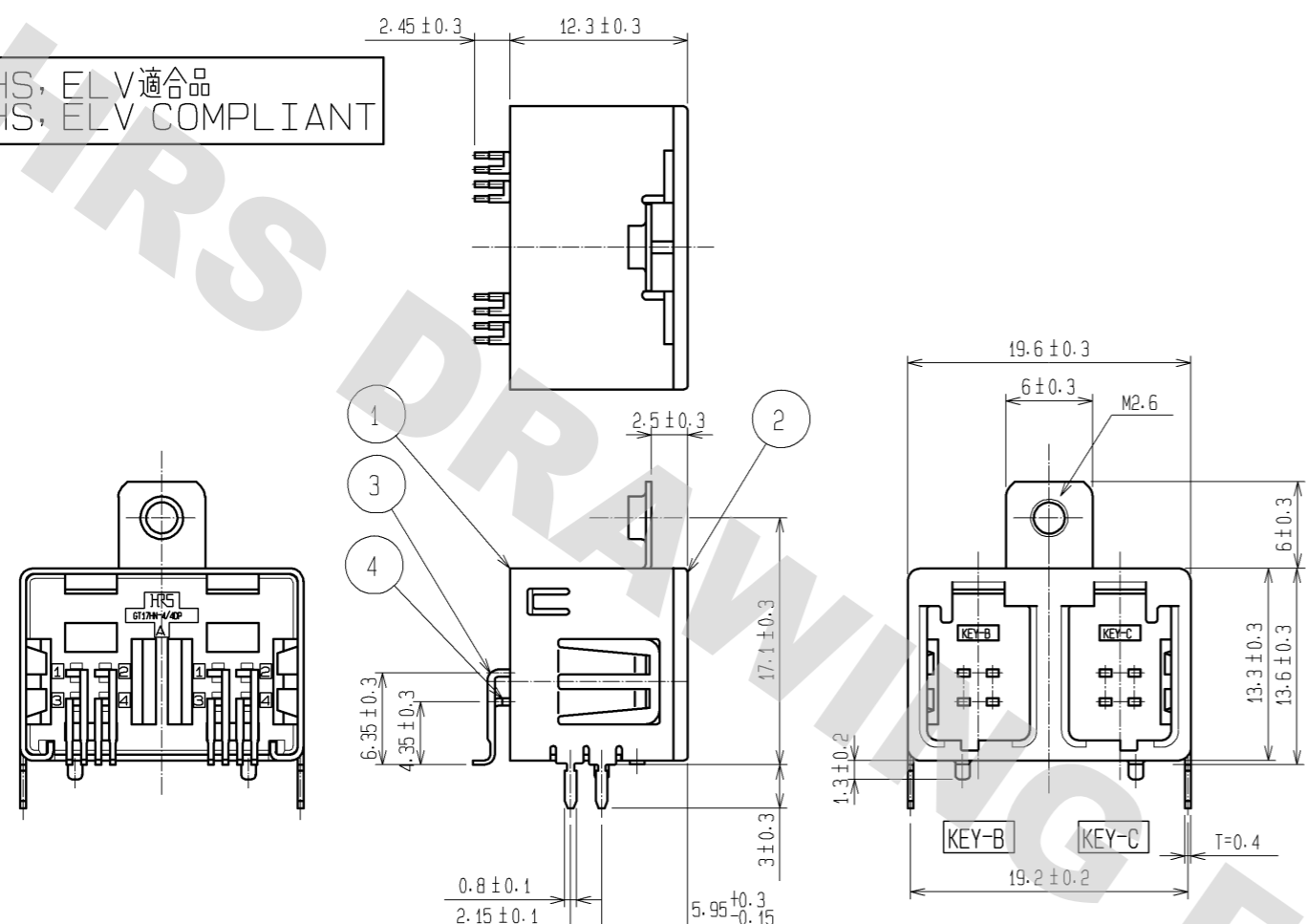
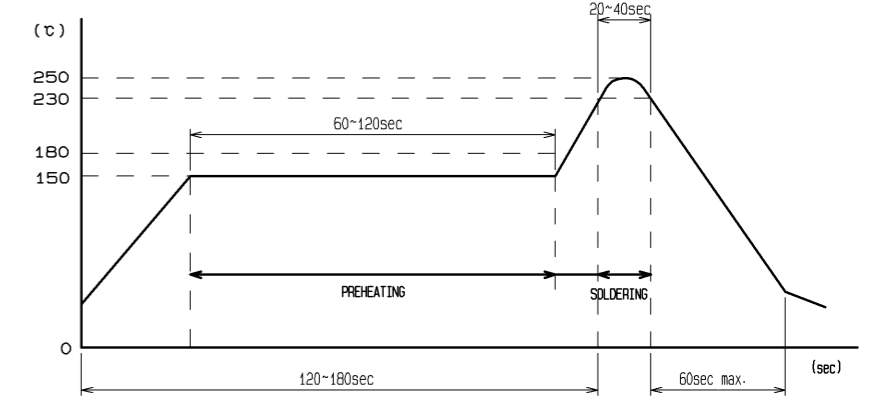


RoHS, ELV適合品
RoHS, ELV COMPLIANT

- Note1. The soldering process is allowed up to twice under the same condition. However, the interval between the first and second process must be maintained at the room temperature.
- リフロー回数: 2回. 但し, 2回目のリフローにおいては, 一度, 室温に戻すこと
- Note2. The temperature indicates the board surface temperature on the connector lead area.
- リフロー温度の測定は, コネクタリード部の基板表面温度を測定のこと.
- Note3. Hand soldering: 280~300°C, 2s max.
- 手半田温度: 280~300°C, 2S以内
- Note4. Coplanarity: 0.1 max.
- 端子平坦度: 0.1以下
- Note5. Recommended thickness of PCB: 1.6mm
- 推奨基板厚: 1.6mm

RECOMMENDED REFLOW PROFILE

IR reflow condition	IR リフロー条件
Preheating area 150°C for 60 to 120 seconds	予熱加熱: 60~120秒, 150°C
Peak Temperature: 250°C	ピーク温度: 250°C
Soldering area 235±5°C or 10 seconds max.	リフロー温度: 230~240°C, 10秒以内
230°C min. for 10~30 seconds	230°C以上: 10~30秒

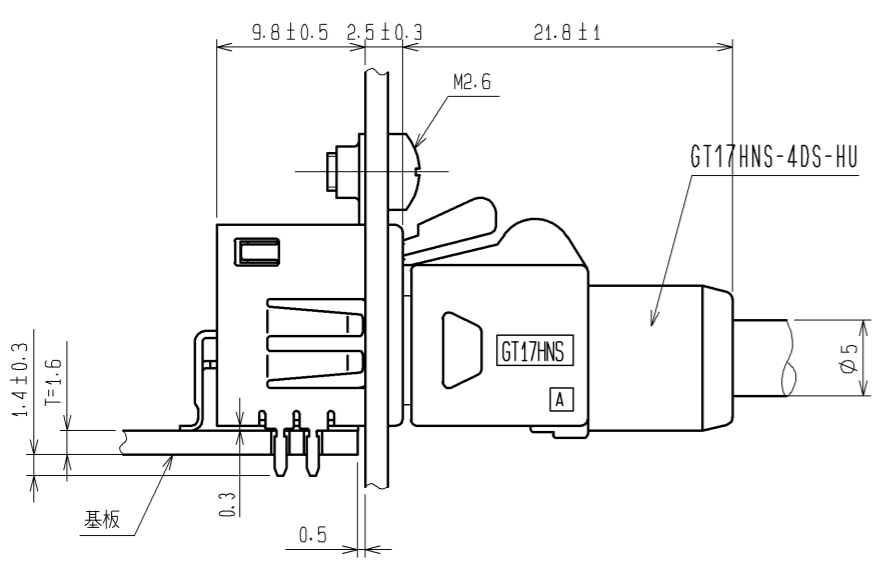


Dimension from PCB surface to screw hole.
13.9±0.1 (基板面からの寸法)

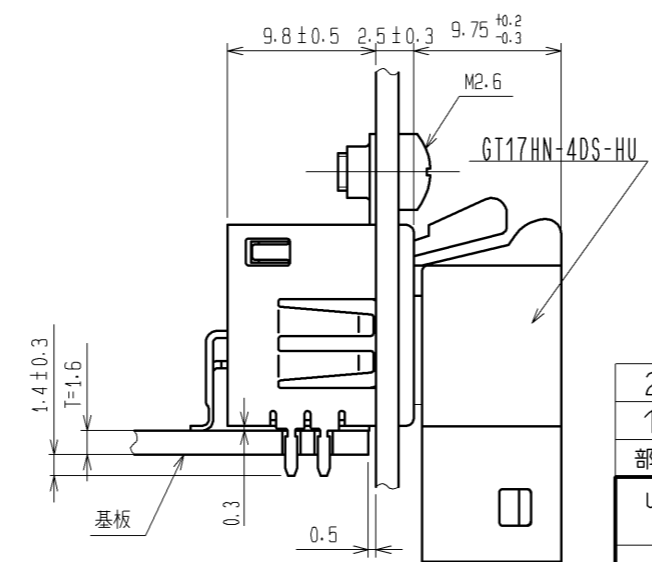
Dimension from PCB surface to connector top.
17.1±0.1 (基板面からの寸法)

基板推奨寸法図
Recommended PCB layout

パネル寸法図
Panel layout



実装状態図
Mated connectors



実装状態図
Mated connectors

2	PPS	LIGHT GRAY	4	BRASS	TIN PLATING
1	COPPER ALLOY	TIN PLATING	3	BRASS	TIN PLATING
部番	材質	処理, 備考	部番	材質	処理, 備考
UNITS mm	SCALE 2 : 1	訂正記事 DIS-T-001604	設計 NH. NAKATA	検図 AR. SHIRAI	年月日 10.02.23
HRS HIROSE ELECTRIC CO., LTD.	承認:	AR. SHIRAI	10.02.19	図番:	EDC3-166814-03
	検図:	AR. SHIRAI	10.02.19	製品名:	GT17HN-4/4DP-2H(BC)
	設計:	NH. NAKATA	10.02.18	製品 コード	CL767-0145-9-00
	製図:	NH. NAKATA	10.02.18		

DRAWING FOR REFERENCE: This is subject to change without notice
08/11/2012

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